

Hardware Kits

HK1



- HK1 contains 2 SSR mounting screws 8-32 x 3/8
- For use with all Crydom heat sinks (Except HS501DR)

HK2

- HK2 contains ground screw 10-32 x 3/8 and 2 bracket screws 6-32 x 1/4
- For use with HS351, HS301, HS271, HS201 HS172, HS151 and HS122 heat sinks



Rev. 080309

ANNEX - ENVIROMENTAL INFORMATION

The environmental information disclosed in this annex including the EIP Pollution logo are in compliance with People's Republic of China Electronic Industry Standard SJ/T11364 – 2006, Marking for Control of Pollution Caused by Electronic Information Products.

| Part Name | Toxic or hazardous Substance and Elements | | | | | | | |
|-------------------|---|-----------------|-----------------|-------------------------------------|--------------------------------------|---|--|--|
| | Lead (Pb) | Mercury (Hg) | Cadmium (Cd) | Hexavalent Chromium (Cr (VI)) | Polybrominated biphenyls (PBB) | Polybrominated diphenyl ethers (PBDE) | | |
| Semiconductor die | 0 | 0 | 0 | 0 | 0 | 0 | | |
| Solder | 0 | 0 | 0 | 0 | 0 | 0 | | |

此附件所标示的包括电子信息产品污染图标的环保信息 符合中华人民共和国电子行业标准 SJ/T11364 - 2006, 电子信息产品污染控制标识要求

| 部件 名称 | 有毒有害物质或元素 | | | | | | | |
|----------|-----------|-----------|-----------|------------------|---------------|-----------------|--|--|
| | 铅 (Pb) | 汞 (Hg) | 镉 (Cd) | 六价铬 (Cr (VI)) | 多溴联苯 (PBB) | 多溴二苯醚 (PBDE) | | |
| 半导体芯片 | 0 | 0 | 0 | 0 | 0 | О | | |
| 焊接点 | 0 | 0 | 0 | 0 | 0 | 0 | | |

